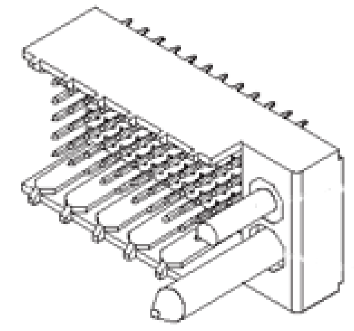
| | |
|---|---|
| **Part Number:** | **0739446016** |
| **Status:** | **Active** |
| **Overview:** | HDM® Backplane Connector System |
| **Description:** | HDM® Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option, 72 Circuits |

**Documents:**

| | |
|---|---|
| 3D Model | Product Specification PS-73670-9999 (PDF) |
| Drawing (PDF) | RoHS Certificate of Compliance (PDF) |

| | |
|---|---|
| **Agency Certification** | |
| CSA | LR19980 |
| UL | E29179 |
| **General** | |
| Product Family | Backplane Connectors |
| Series | 73944 |
| Application | Backplane |
| Component Type | PCB Header |
| Overview | HDM® Backplane Connector System |
| Product Name | HDM® |
| UPC | 800753005594 |
| **Physical** | |
| Circuits (Loaded) | 72 |
| Circuits (maximum) | 72 |
| Color - Resin | Black, Natural |
| Durability (mating cycles max) | 250 |
| First Mate / Last Break | No |
| Flammability | 94V-0 |
| Guide to Mating Part | Yes |
| Keying to Mating Part | Yes |
| Material - Metal | Phosphor Bronze, Stainless Steel |
| Material - Plating Mating | Gold |
| Material - Plating Termination | Tin |
| Material - Resin | High Temperature Thermoplastic |
| Net Weight | 5.394/g |
| Number of Columns | 12 |
| Number of Pairs | Open Pin Field |
| Number of Rows | 6 |
| Orientation | Vertical |
| PC Tail Length | 3.50mm |
| PCB Locator | Yes |
| PCB Retention | None |
| PCB Thickness - Recommended | 2.50mm |
| Packaging Type | Tube |
| Pitch - Mating Interface | 2.00mm |
| Pitch - Termination Interface | 2.00mm |
| Plating min - Mating | 0.762µm |
| Plating min - Termination | 2.540µm |
| Polarized to PCB | No |
| Stackable | No |
| Surface Mount Compatible (SMC) | No |
| Temperature Range - Operating | -55°C to +105°C |
| Termination Interface: Style | Through Hole |

**Electrical**


*Series image - Reference only*

**EU ELV**
**Not Relevant**

**EU RoHS** **China RoHS**
**Compliant**

**REACH SVHC**
Contains SVHC(2014 December 17): No

**Halogen-Free Status**
**Low-Halogen**

**Need more information on product environmental compliance?**

Email productcompliance@molex.com
Please visit the Contact Us section for any non-product compliance questions.

| | |
|---|---|
| China ROHS | Green Image |
| ELV | Not Relevant |

**Search Parts in this Series**
73944 Series

**Mates With**
73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

**Application Tooling** | **FAQ**
*Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.*

**Global**

| Description | Product # |
|---|---|
| Extraction Tool | 0621001000 |
| Backplane Insertion | 0621001400 |
| Signal Contact Tool | |

|  |  |
|---|---|
| Current - Maximum per Contact | 1.0A |
| Data Rate | 1.0 Gbps |
| Shielded | No |
| Voltage - Maximum | 250V AC |

**Solder Process Data**

|  |  |
|---|---|
| Duration at Max. Process Temperature (seconds) | 040 |
| Lead-freeProcess Capability | SMC&WAVE |
| Max. Cycles at Max. Process Temperature | 003 |
| Process Temperature max. C | 260 |

**Material Info**

**Reference - Drawing Numbers**

|  |  |
|---|---|
| Product Specification | PS-73670-9999 |
| Sales Drawing | SD-73944-001 |

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This document was generated on 06/26/2015

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